Asada Chemical

TECHNICAL REPORT

Functional materials

GX82S1

Die Attach Paste

1.Introduction

Die Attach Paste “GX82S1“ is epoxy resin based and solvent free Type paste.
The highest thermal conductivity (19.1W/mK)
Good reflow performance due to lower moisture absorption resin system.
GX82S 1 is effectively used for power IC, transistor..

2.Features

1) Good workability for dispensing due to solvent free and one liquid type paste.
2) Highest thermal conductivity(19.1W/mK)

3. General Property

Properties		Unit	Typical Value	Test Method
Appearance		-	Silver Filled Paste	Visual
Viscosity at 25C		Pa･s	120	E-Type Viscometer 0.5rpm (3 ゜cone)
Thixotropic Index		-	6.0	0.5rpm/5.0rpm
Non Volatile		wt%	82.0	180C×2hr
Silver Content		wt%	79	600C×3hr
Die shear strength	25C 300C	Kgf	3.5 2.8	Frame : Cu/PPF Chip Size : 2x2mm
Volume Resistivity		Ohm･cm	8×10^{-6}	Cure : 200Cx90min. Measurement: Room Temp.
Glass Transition Temperature		C	160	TMA
Modules（25C）	25C	GPa	16.5	DMA
	260C		7.8	
CTE	Alpha1	Ppm	40	TMA
	Alpha2		125	
Ionic Impurity	Na Cl	ppm	6 1	Atomic Absorption Ionchromatography
Thermal Conductivity		W/m K	21.1	Laser Flash

4. Standard Curing Condition

[1st Step] **170℃ x120min** (Keeping time) in Oven

5. Remarks

Storage condition is -30 to -15℃